

1MHz, High-Efficiency, Step-Up Converter for 2 to 8 White LEDs

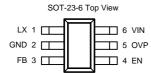
### Features

- Wide Input Voltage from 2.7V to 6V
- 0.25V Reference Voltage
- Fixed 1MHz Switching Frequency
- High Efficiency up to 87%
- 100Hz to 100KHz PWM brightness control frequency
- Open-LED Protection
- Under Voltage Lockout Protection
- Over Temperature Protection
- <1mA Quiescent Current during Shutdown</p>
- SOT-23-6 Package
- Lead Free Available (RoHS Compliant)

# Applications

- White LED Display Backlighting
- Cell Phone and Smart Phone
- PDA, PMP, MP3
- Digital Camera

## **Pin Configuration**



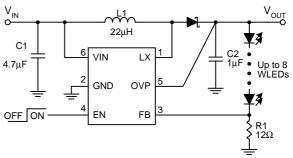
# **General Description**

The APW7136A/B/C is a current-mode and fixed frequency boost converter with an integrated N-FET to drive up to 8 white LEDs in series.

The series connection allows the LED current to be identical for uniform brightness. Its low on-resistance of N-FET and feedback voltage reduce power loss and achieves high efficiency. Fast 1MHz current-mode PWM operation is available for input and output capacitors and a small inductor while minimizing ripple on the input supply. The OVP pin monitors the output voltage and stop switching if exceeds the over-voltage threshold. An internal soft-start circuit eliminates the inrush current during start-up.

The APW7136A/B/C also integrates under-voltage lockout, over-temperature protection and current limit circuits. The APW7136/A/B/C is available in a SOT-23-6 package.

# **Simplified Application Circuit**



# Ordering and Marking Information

	<ul> <li>Lead Free Code</li> <li>Handling Code</li> <li>Temperature Range</li> <li>Package Code</li> <li>OVP Voltage Code</li> </ul>	OVP Voltage Code A: 20V B: 28V C: 35V Package Code C : SOT-23-6 Operating Ambient Temperature Range I : -40 to 85°C Handling Code TR : Tape & Reel Lead Free Code L : Lead Free Device
APW7136YCI : CFYX	Y - OVP Voltage Code X - Date Code	

Note: ANPEC lead-free products contain molding compounds/die attach materials and 100% matte tin plate termination finish; which are fully compliant with RoHS and compatible with both SnPb and lead-free soldering operations. ANPEC lead-free products meet or exceed the lead-free requirements of IPC/JEDEC J STD-020C for MSL classification at lead-free peak reflow temperature.

ANPEC reserves the right to make changes to improve reliability or manufacturability without notice, and advise customers to obtain the latest version of relevant information to verify before placing orders.

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### Absolute Maximum Ratings (Note 1)

Symbol	Parameter	Rating	Unit
V <sub>IN</sub>	VIN Supply Voltage (VIN to GND)	-0.3 ~ 7	V
	FB, EN to GND Voltage	-0.3 ~ V <sub>IN</sub>	V
$V_{\text{LX}}$	LX to GND Voltage	-0.3 ~ 38	V
V <sub>OVP</sub>	OVP to GND Voltage	-0.3 ~ 38	V
TJ	Maximum Junction Temperature	150	°C
$T_{STG}$	Storage Temperature Range	-65 ~ 150	°C
T <sub>SDR</sub>	Maximum Lead Soldering Temperature, 10 seconds	260	°C

Note 1: Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

### Thermal Characteristics (Note 2)

S	ymbol	Parameter	Rating	Unit	
	$\theta_{JA}$	Junction to Ambient Thermal Resistance	SOT-23-6	250	°C/W

Note 2:  $\theta_{JA}$  is measured with the component mounted on a high effective thermal conductivity test board in free air. The exposed pad of package is soldered directly on the PCB.

## Recommended Operating Conditions (Note 3)

Symbol	Parameter	Range	Unit
V <sub>IN</sub>	VIN Input Voltage	2.7~ 6	V
V <sub>OUT</sub>	Converter Output Voltage	Up to 32	V
CIN	Input Capacitor	4.7 or higher	μF
C <sub>OUT</sub>	Output Capacitor	0.68 or higher	μF
L1	Inductor	6.8 to 47	μH
T <sub>A</sub>	Ambient Temperature	-40 to 85	°C
TJ	Junction Temperature	-40 to 125	°C

Note 3: Refer to the application circuit for further information.

## **Electrical Characteristics**

(Refer to Figure 1 in the "Typical Application Circuits". These specifications apply over  $V_{IN} = 3.6V$ ,  $T_A = -40^{\circ}$ C to 85°C, unless otherwise noted. Typical values are at  $T_A = 25^{\circ}$ C.)

Symbol	Parameter	Test Condition	APW7136A/B/C			Unit			
Symbol	Parameter	Test Condition	Min.	Тур.	Max.	Unit			
SUPPLY VOLTAGE AND CURRENT									
V <sub>IN</sub>	Input Voltage Range	$T_A = -40 \sim 85^{\circ}C, T_J = -40 \sim 125^{\circ}C$	2.7	-	6	V			
I <sub>DD1</sub>		V <sub>FB</sub> = 1.3V, no switching	70	100	130	μA			
I <sub>DD2</sub>	Input DC bias current	FB = GND, switching	-	1	2	mA			
I <sub>SD</sub>		EN = GND	-	-	1	μA			
UNDER V	OLTAGE LOCKOUT								
	UVLO Threshold Voltage	V <sub>IN</sub> Rising	2.0	2.2	2.4	V			
	UVLO Hysteresis Voltage		50	100	150	mV			



# **Electrical Characteristics (Cont.)**

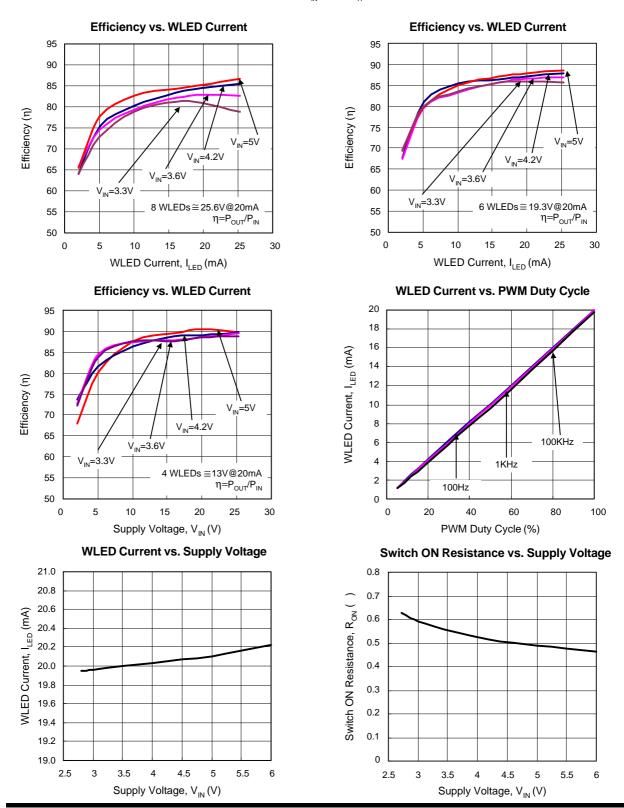
(Refer to Figure 1 in the "Typical Application Circuits". These specifications apply over  $V_{IN} = 3.6V$ ,  $T_A = -40^{\circ}C$  to 85°C, unless otherwise noted. Typical values are at  $T_A = 25^{\circ}C$ .)

Cumhal	Demonster	Test Condition	AP	W7136A/	B/C	Unit
Symbol	Parameter	Test Condition	Min.	Тур.	Max.	Unit
REFEREN	ICE AND OUTPUT VOLTAGES					
V		T <sub>A</sub> = 25°C	237	250	263	mV
$V_{REF}$	Regulated Feedback Voltage	$T_A = -40 \sim 85^{\circ}C (T_J = -40 \sim 125^{\circ}C)$	230	-	270	mv
I <sub>FB</sub>	FB Input Current		-50	-	50	nA
INTERNA	L POWER SWITCH					
F <sub>sw</sub>	Switching Frequency	FB=GND	0.8	1.0	1.2	MHz
R <sub>ON</sub>	Power Switch On Resistance		-	0.6	-	Ω
I <sub>LIM</sub>	Power Switch Current Limit		0.7	0.9	1.2	Α
	LX Leakage Current	$V_{EN}=0V$ , $V_{LX}=0V$ or 5V, $V_{IN}=5V$	-1	-	1	μA
D <sub>MAX</sub>	LX Maximum Duty Cycle		92	95	98	%
OUTPUT	OVER VOLTAGE PROTECTION	-				
		APW7136A	-	20	-	
V <sub>OVP</sub>	Over Voltage Threshold	APW7136B	-	28	-	V
		APW7136C	-	35	-	1
	OVP Hysteresis		-	3	-	V
	OVP Leakage Current	V <sub>OVP</sub> =30V, EN=VIN	-	-	50	μA
ENABLE	AND SHUTDOWN	•				
$V_{TEN}$	EN Voltage Threshold	V <sub>EN</sub> Rising	0.4	0.7	1	V
	EN Voltage Hysteresis		-	0.1	-	V
I <sub>LEN</sub>	EN Leakage Current	$V_{EN} = 0 \sim 5V, V_{IN} = 5V$	-1	-	1	μA
OVER-TE	MPERATURE PROTECTION		·	•	•	•
T <sub>OTP</sub>	Over-Temperature Protection	T <sub>J</sub> Rising	-	150	-	°C
	Over-Temperature Protection Hysteresis		-	40	-	°C



## **Typical Operating Characteristics**

(Refer to Figure 1 in the section "Typical Application Circuits", V<sub>IN</sub>=3.6V, T<sub>A</sub>=25°C, 8WLEDs unless otherwise specified)

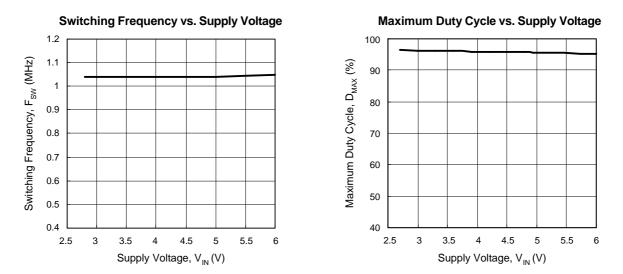


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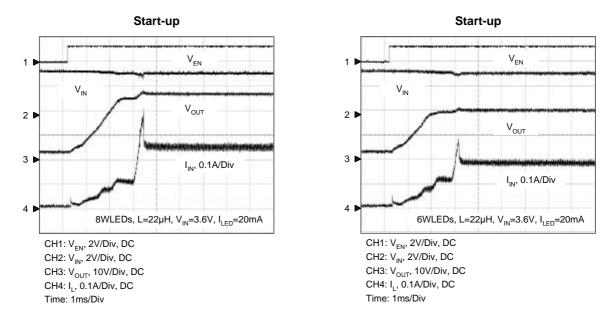
### **Typical Operating Characteristics**

(Refer to Figure 1 in the section "Typical Application Circuits", V<sub>IN</sub>=3.6V, T<sub>A</sub>=25°C, 8WLEDs unless otherwise specified)



### **Operating Waveforms**

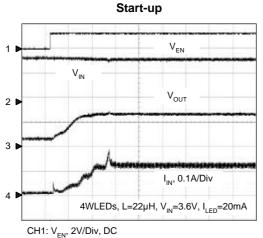
(Refer to the application circuit in the section "Typical Application Circuits",  $V_{IN}$ =3.6V,  $T_A$ =25°C, 8WLEDs unless otherwise specified )



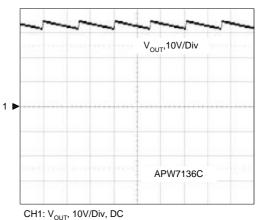


## **Operating Waveforms (Cont.)**

(Refer to the application circuit in the section "Typical Application Circuits", V<sub>IN</sub>=3.6V, T<sub>A</sub>=25°C, 8WLEDs unless otherwise specified)

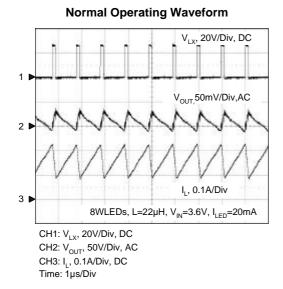


CH2: VIN, 2V/Div, DC CH3: V<sub>OUT</sub>, 10V/Div, DC CH4: I, , 0.1A/Div, DC Time: 1ms/Div



**Open-LED Protection** 



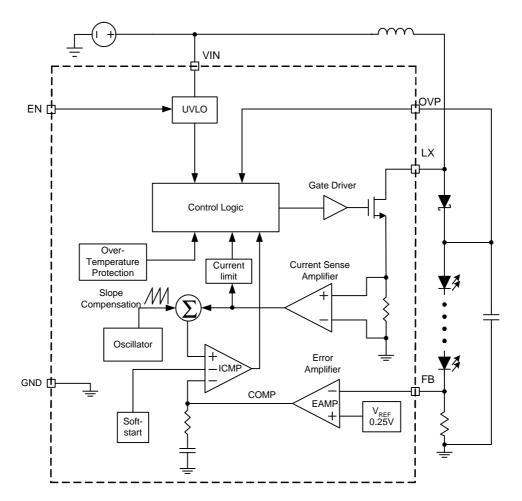




# **Pin Descriptions**

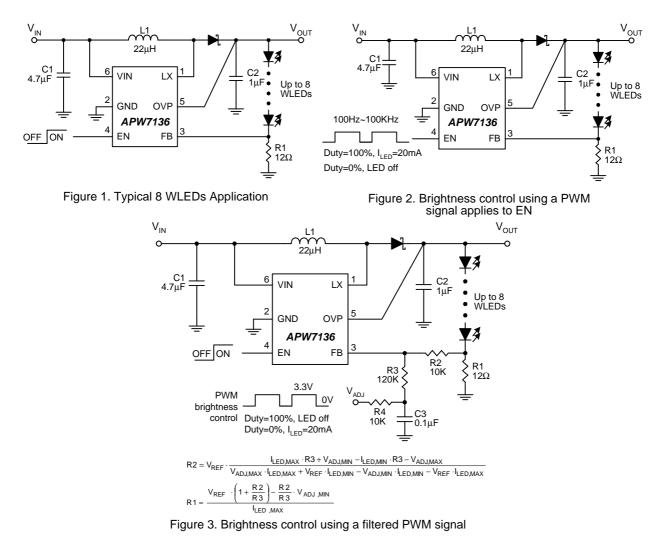
Pin No.	Name	Function Description
1	LX	Switch pin. Connect this pin to inductor/diode here.
2	GND	Power and signal ground pin.
3	FB	Feedback Pin. Reference voltage is 0.25V. Connect this pin to cathode of the lowest LED and resistor (R1). Calculate resistor value according to R1= $0.25$ V/I <sub>LED</sub> .
4	EN	Enable Control Input. Forcing this pin above 1.0V enables the device, or forcing this pin below 0.4V to shut it down. In shutdown, all functions are disabled to decrease the supply current below 1 $\mu$ A. <b>Do not leave this pin floating.</b>
5	OVP	Over Voltage Protection Input Pin. OVP is connected to the output capacitor of the converter.
6	VIN	Main Supply Pin. Must be closely decoupled to GND with a $4.7\mu F$ or greater ceramic capacitor.

### **Block Diagram**





## **Typical Application Circuits**



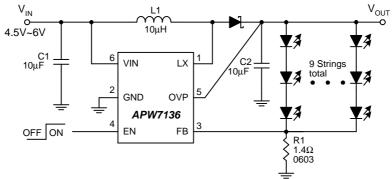


Figure 4. Circuit for driving 27 WLEDs



## **Function Descriptions**

#### Main Control Loop

The APW7136 is a constant frequency current-mode switching regulator. During normal operation, the internal N-channel power MOSFET is turned on each cycle when the oscillator sets an internal RS latch and turned off when an internal comparator (ICMP) resets the latch. The peak inductor current at which ICMP resets the RS latch is controlled by the voltage on the COMP node, which is the output of the error amplifier (EAMP). An external resistive divider connected between  $V_{OUT}$  and ground allows the EAMP to receive an output feedback voltage  $V_{FB}$  at FB pin. When the load current increases, it causes a slightly decrease in  $V_{FB}$  relative to the 0.25V reference, which in turn causes the COMP voltage to increase until the average inductor current matches the new load current.

#### VIN Under-Voltage Lockout (UVLO)

The Under-Voltage Lockout (UVLO) circuit compares the input voltage at VIN with the UVLO threshold (2.2V, typical) to ensure the input voltage is high enough for reliable operation. The 100mV (typ) hysteresis prevents supply transients from causing a restart. Once the input voltage exceeds the UVLO rising threshold, startup begins. When the input voltage falls below the UVLO falling threshold, the controller turns off the converter.

#### Soft-Start

The APW7136 has a built-in soft-start to control the Nchannel MOSFET current rise during start-up. During softstart, an internal ramp, connected to one of the inverting inputs, raise up to replace the output voltage of error amplifier until the ramp voltage reaches the  $V_{COMP}$ .

#### **Current-Limit Protection**

The APW7136 monitors the inductor current, flowing through the N-channel MOSFET, and limits the current peak at current-limit level to prevent loads and the APW7136 from damages during overload conditions.

#### **Over-Temperature Protection (OTP)**

The over-temperature circuit limits the junction temperature of the APW7136. When the junction temperature exceeds 150°C, a thermal sensor turns off the power MOSFET, allowing the devices to cool. The thermal sensor allows the converters to start a soft-start process and regulate the output voltage again after the junction temperature cools by 40°C. The OTP designed with a 40°C hysteresis lowers the average Junction Temperature (T<sub>J</sub>) during continuous thermal overload conditions, increasing the lifetime of the device.

#### Enable/Shutdown

Driving EN to ground places the APW7136 in shutdown mode. When in shutdown, the internal power MOSFET turns off, all internal circuitry shuts down and the quiescnet supply current reduces to  $1\mu$ A maximum.

This pin also could be used as a digital input allowing brightness control using a PWM signal from 100Hz to 100KHz. The 0% duty cycle of PWM signal corresponds to zero LEDs current and 100% corresponds to full one.

#### **Open-LED Protection**

In driving LED applications, the feedback voltage on FB pin falls down if one of the LEDs, in series, is failed. Meanwhile, the converter unceasingly boosts the output voltage like a open-loop operation. Therefore, an overvoltage protection (OVP), monitoring the output voltage via OVP pin, is integrated into the chip to prevent the LX and the output voltages from exceeding their maximum voltage ratings. When the voltage on the OVP pin rises above the OVP threshold, the converter stops switching and prevents the output voltage from rising. The converter can work again when the OVP voltage falls below the falling of OVP voltage threshold.



## **Application Information**

#### Input Capacitor Selection

The input capacitor  $(C_{IN})$  reduces the ripple of the input current drawn from the input supply and reduces noise injection into the IC. The reflected ripple voltage will be smaller when an input capacitor with larger capacitance is used. For reliable operation, it is recommended to select the capacitor with maximum voltage rating at least 1.2 times of the maximum input voltage. The capacitors should be placed close to the VIN and GND.

#### **Inductor Selection**

Selecting an inductor with low dc resistance reduces conduction losses and achieves high efficiency. The efficiency is moderated whilst using small chip inductor which operates with higher inductor core losses. Therefore, it is necessary to take further consideration while choosing an adequate inductor. Mainly, the inductor value determines the inductor ripple current: larger inductor value results in smaller inductor ripple current and lower conduction losses of the converter. However, larger inductor value generates slower load transient response. A reasonable design rule is to set the ripple current,  $\Delta I_L$ , to be 30% to 50% of the maximum average inductor current,  $I_{L(AVG)}$ . The inductor value can be obtained as below,

$$L \ge \left(\frac{V_{IN}}{V_{OUT}}\right)^{2} \times \frac{V_{OUT} - V_{IN}}{F_{SW} \cdot I_{OUT(MAX)}} \times \frac{\eta}{\left(\frac{\Delta I_{L}}{I_{L(AVG)}}\right)}$$

where

 $V_{IN}$  = input voltage

 $F_{sw}$  = switching frequency in MHz

 $I_{OUT}$  = maximum output current in amp.

= Efficiency

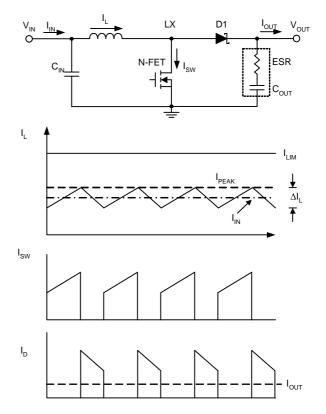
$$\Delta I_{L}/I_{L(AVG)} =$$
 inductor ripple current/average current  
(0.3 to 0.5 typical)

To avoid saturation of the inductor, the inductor should be rated at least for the maximum input current of the converter plus the inductor ripple current. The maximum input current is calculated as below:

$$I_{\text{IN(MAX)}} = \frac{I_{\text{OUT(MAX)}} \cdot V_{\text{OUT}}}{V_{\text{IN}} \cdot \eta}$$

The peak inductor current is calculated as the following equation:

$$I_{\mathsf{PEAK}} = I_{\mathsf{IN}(\mathsf{MAX})} + \frac{1}{2} \cdot \frac{V_{\mathsf{IN}} \cdot \left(V_{\mathsf{OUT}} - V_{\mathsf{IN}}\right)}{V_{\mathsf{OUT}} \cdot L \cdot F_{\mathsf{SW}}}$$



#### **Output Capacitor Selection**

The current-mode control scheme of the APW7136 allows the usage of tiny ceramic capacitors. The higher capacitor value provides good load transients response. Ceramic capacitors with low ESR values have the lowest output voltage ripple and are recommended. If required, tantalum capacitors may be used as well. The output ripple is the sum of the voltages across the ESR and the ideal output capacitor.

$$V_{OUT} = V_{ESR} + V_{COUT}$$
$$\Delta V_{COUT} \approx \frac{I_{OUT}}{C_{OUT}} \cdot \left(\frac{V_{OUT} - V_{IN}}{V_{OUT} \cdot F_{SW}}\right)$$

$$\Delta V_{ESR} \approx I_{PEAK} \cdot R_{ESR}$$
 where  $I_{_{PEAK}}$  is the peak inductor current.

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# **Application Information (Cont.)**

#### **Output Capacitor Selection (Cont.)**

For ceramic capacitor application, the output voltage ripple is dominated by the  $\Delta V_{COUT}$ . When choosing the input and output ceramic capacitors, the X5R or X7R with their good temperature and voltage characteristics are recommended.

#### Setting the LED Current

In figure 1, the converter regulates the voltage on FB pin, connected with the cathod of the lowest LED and the current-sense resistor R1, at 0.25V (typical). Therefore the current ( $I_{LED}$ ), flowing via the LEDs and the R1, is calculated by the following equation:

I<sub>LED</sub> = 0.25V/R1

#### **Diode Selection**

To achieve high efficiency, a Schottky diode must be used. The current rating of the diode must meet the peak current rating of the converter.

#### **Recommended Inductor Selection**

Designator	Manufacturer	Part Number	Inductance (µH)	Max DCR (ohm)	Saturation Current (A)	Dimensions L x W x H (mm <sup>3</sup> )
L1	GOTREND	GTSD32	22	0.592	0.52	3.85 x 3.85 x 1.8

#### **Recommended Capacitor Selection**

Designator	Manufacturer	Manufacturer Part Number		TC Code	Rated Voltage (V)	Case size
C1	Murata	GRM188R60J475KE19	4.7	X5R	6.3	0603
C2	Murata	GRM21BR71H105KA12	1.0	X7R	50	0805

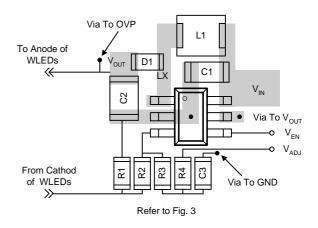
#### **Recommended Diode Selection**

Designator	Manufacturer	Part Number	Maximum average forward rectified current (A)	Maximum repetitive peak reverse voltage (V)	Case size
D1	Zowie	MSCD106	1.0	60	0805
D1	Zowie	MSCD104	1.0	40	0805

### Layout Consideration

For all switching power supplies, the layout is an important step in the design; especially at high peak currents and switching frequencies. If the layout is not carefully done, the regulator might show noise problems and duty cycle jitter.

- 1. The input capacitor should be placed close to the VIN and GND. Connecting the capacitor with VIN and GND pins by short and wide tracks without using any vias for filtering and minimizing the input voltage ripple.
- The inductor should be placed as close as possible to the LX pin to minimize length of the copper tracks as well as the noise coupling into other circuits.
- 3. Since the feedback pin and network is a high impedance circuit, the feedback network should be routed away from the inductor. The feedback pin and feedback network should be shielded with a ground plane or track to minimize noise coupling into this circuit.
- 4. A star ground connection or ground plane minimizes ground shifts and noise is recommended.

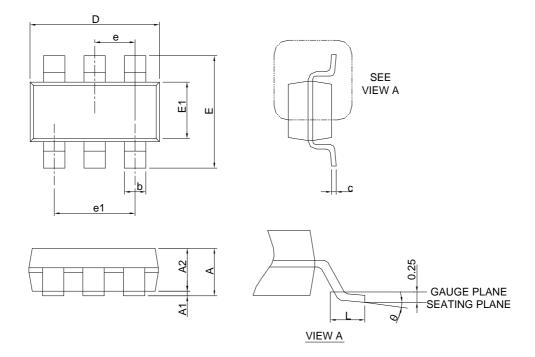


Optimized APW7136 Layout



# Package Information

SOT-23-6



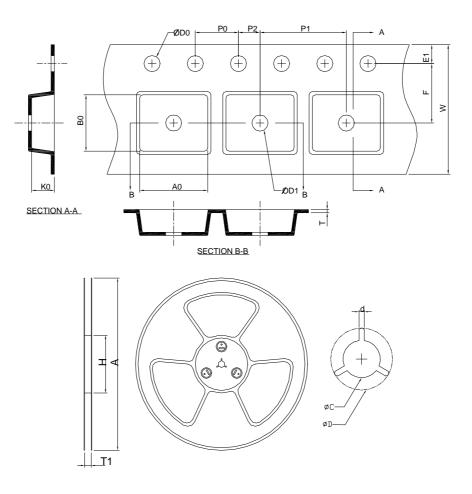
Ş	SOT-23-6					
SY MBO_	MILLIM	ETERS	INCHES			
L L	MIN.	MAX.	MIN.	MAX.		
Α		1.45		0.057		
A1	0.00	0.15	0.000	0.006		
A2	0.90	1.30	0.035	0.051		
b	0.30 0.50		0.012	0.020		
С	0.08	0.22	0.003	0.009		
D	2.70	3.10	0.106	0.122		
Е	2.60	3.00	0.102	0.118		
E1	1.40	1.80	0.055	0.071		
е	0.95	BSC	0.03	7 BSC		
e1	1.90 BSC		0.075 BSC			
L	0.30	0.60	0.012	0.024		
θ	0°	8°	0°	8°		

Note : 1. Follow JEDEC TO-178 AB.

2. Dimension D and E1 do not include mold flash, protrusions or gate burrs. Mold flash, protrusion or gate burrs shall not exceed 10 mil per side.



# **Carrier Tape & Reel Dimensions**



Application	Α	Н	T1	С	d	D	W	E1	F
	178.0± 2.00	50 MIN.	8.4+2.00 -0.00	13.0+0.50 -0.20	1.5 MIN.	20.2 MIN.	8.0 <b>±</b> 0.30	1.75 <b>±</b> 0.10	3.5 <b>±</b> 0.05
SOT-23-6	P0	P1	P2	D0	D1	Т	A0	B0	K0
	4.0 <b>±</b> 0.10	4.0 <b>±</b> 0.10	2.0 <b>±</b> 0.10	1.5+0.10 -0.00	1.5 MIN.	0.6+0.00 -0.40	3.20 <b>±</b> 0.20	3.10 ±0.20	1.50 ±0.20

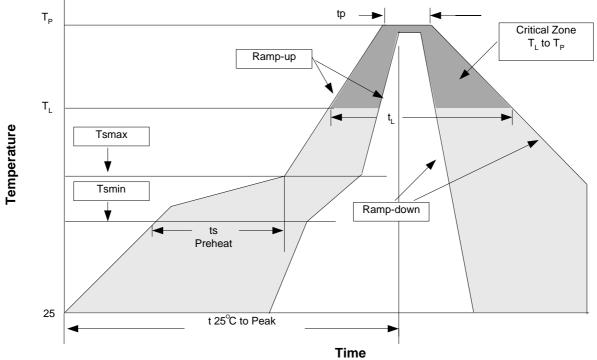
(mm)

## **Devices Per Unit**

Package Type	Unit	Quantity	
SOT-23-6	Tape & Reel	3000	



### Reflow Condition (IR/Convection or VPR Reflow)



# **Reliability Test Program**

Test item	Method	Description	
SOLDERABILITY	MIL-STD-883D-2003	245°C, 5 sec	
HOLT	MIL-STD-883D-1005.7	1000 Hrs Bias @125°C	
PCT	JESD-22-B, A102	168 Hrs, 100%RH, 121°C	
TST	MIL-STD-883D-1011.9	-65°C~150°C, 200 Cycles	
ESD	MIL-STD-883D-3015.7	VHBM > 2KV, VMM > 200V	
Latch-Up	JESD 78	10ms, 1 <sub>tr</sub> > 100mA	

## **Classification Reflow Profiles**

Profile Feature	Sn-Pb Eutectic Assembly	Pb-Free Assembly
Average ramp-up rate $(T_L \text{ to } T_P)$	3°C/second max.	3°C/second max.
Preheat - Temperature Min (Tsmin) - Temperature Max (Tsmax) - Time (min to max) (ts)	100°C 150°C 60-120 seconds	150°C 200°C 60-180 seconds
Time maintained above: - Temperature (T <sub>L</sub> ) - Time (t <sub>L</sub> )	183°C 60-150 seconds	217°C 60-150 seconds
Peak/Classification Temperature (Tp)	See table 1	See table 2
Time within 5°C of actual Peak Temperature (tp)	10-30 seconds	20-40 seconds
Ramp-down Rate	6°C/second max.	6°C/second max.
Time 25°C to Peak Temperature	6 minutes max.	8 minutes max.

Note: All temperatures refer to topside of the package. Measured on the body surface.

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### **Classification Reflow Profiles (Cont.)**

 Table 1.
 SnPb Eutectic Process – Package Peak Reflow Temperatures

Package Thickness	Volume mm <sup>3</sup> <350	Volume mm <sup>3</sup> <sup>3</sup> 350	
<2.5 mm	240 +0/-5°C	225 +0/-5°C	
≥2.5 mm	225 +0/-5°C	225 +0/-5°C	

Table 2. Pb-free Process – Package Classification Reflow Temperatures

Package Thickness	Volume mm <sup>3</sup> <350	Volume mm <sup>3</sup> 350-2000	Volume mm <sup>3</sup> >2000	
<1.6 mm	260 +0°C*	260 +0°C*	260 +0°C*	
1.6 mm – 2.5 mm	260 +0°C*	250 +0°C*	245 +0°C*	
≥2.5 mm	250 +0°C*	245 +0°C*	245 +0°C*	
* Tolerance: The device manufacturer/supplier <b>shall</b> assure process compatibility up to and including the stated classification temperature (this means Peak reflow temperature +0°C. For example 260°C+0°C) at the rated MSL				

level.

### **Customer Service**

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